

NEWSLETTER
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Huawei Unveils High-Performance Kirin 9050 Pro Chip

Huawei has launched the Kirin 9050 Pro, its first high-performance processor using logic-folding technology, which shortens signal paths and reduces latency. Huawei's research and development (R&D) spending reached 121.38 billion yuan (about \$17.9 billion) in the first half of 2026, while smartphone shipments rose 19.4% year-on-year, giving Huawei a 22.6% domestic market share. **(Xinhua)**

China Achieves High-Speed Earth-Moon Laser Communication

China has established the first two-way high-speed laser communication link between Earth and the Moon, spanning about 400,000 kilometers. The system achieved uplink speeds of 1.25 Mbps and downlink speeds of 100 Mbps, significantly improving data transmission over conventional microwave links. The technology could support future manned lunar missions, lunar research stations and deep-space exploration. **(People's Daily)**

Guangdong Strengthens AI Hardware Manufacturing

China's Guangdong province is leveraging its manufacturing ecosystem to commercialize artificial intelligence (AI) hardware at scale. The province covers all 31 major manufacturing categories and has China's largest number of large industrial enterprises. Its integrated supply chains, engineering capabilities and production capacity are accelerating the transition of AI innovations from prototypes to affordable physical products. **(China Daily)**

Shenzhen's AI Hardware Ecosystem Gains Momentum

Shenzhen is accelerating AI hardware commercialization through dense industrial clusters and integrated supply chains. From January to July, AI product sales in Huaqiangbei rose more than 55% year-on-year, with AI glasses sales doubling and drone and robot sales increasing 60–70%. Nanshan District has also established 500 million yuan (about \$74.55 million) in seed and angel funds. **(China Daily)**

China Develops Lightweight AI Agent for Materials Research

Chinese researchers have developed MatBrain, a dual-model artificial intelligence (AI) agent for materials research. It improved prediction accuracy by 66% over large models while reducing hardware deployment costs by 95%. The system combines a 30-billion-parameter reasoning model with a 14-billion-parameter execution model, supporting material design, property prediction, screening and synthesis planning. **(Xinhua)**